# TOSHIBA

TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOSIV)

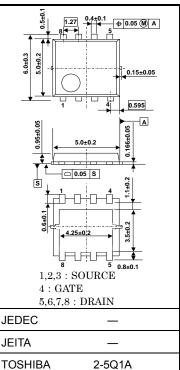
# **TPCA8103**

Lithium Ion Battery Applications Notebook PC Applications Portable Equipment Applications

- Small footprint due to small and thin package
- Low drain-source ON resistance:  $RDS(ON) = 3.1 \text{ m}\Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 45S$  (typ.)
- Low leakage current:  $I_{DSS} = -10 \ \mu A \ (max) \ (V_{DS} = -30 \ V)$
- Enhancement mode:  $V_{th} = -0.8$  to -2.0 V ( $V_{DS} = -10$  V,  $I_D = -1$  mA)

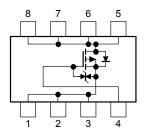
#### Maximum Ratings (Ta = 25°C)

Characte	ristics	Symbol	Rating	Unit	
Drain-source voltage		V <sub>DSS</sub>	-30	V	
Drain-gate voltage (R	$d_{GS} = 20 \text{ k}\Omega$ )	V <sub>DGR</sub>	-30	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	۱ <sub>D</sub>	- 40	Α	
Drain current	Pulsed (Note 1)	I <sub>DP</sub>	-120	~	
Drain power dissipati	on (Tc=25°C)	PD	45	W	
Drain power dissipati	on (t = 10 s) (Note 2a)	PD	2.8	W	
Drain power dissipati	on (t = 10 s) (Note 2b)	PD	1.6	W	
Single pulse avalanch	ne energy (Note 3)	EAS	208	mJ	
Avalanche current		I <sub>AR</sub>	- 40	A	
Repetitive avalanche (T	energy c=25°C) (Note 4)	E <sub>AR</sub>	4.5	mJ	
Channel temperature	:	T <sub>ch</sub>	150	°C	
Storage temperature	range	T <sub>stg</sub>	–55 to 150	°C	



Weight: 0.076 g (typ.)

## **Circuit Configuration**



Note: For (Note 1), (Note 2), (Note 3), (Note 4), please refer to the next page.

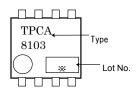
This transistor is an electrostatic sensitive device. Please handle with caution.

Unit: mm

### **Thermal Characteristics**

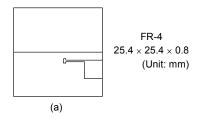
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case (Tc=25°C)	R <sub>th (ch-c)</sub>	2.78	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R <sub>th (ch-a)</sub>	44.6	°C/W
Thermal resistance, channel to ambient $(t = 10 \text{ s})$ (Note 2b)	R <sub>th (ch-a)</sub>	78.1	°C/W

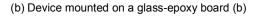
#### Marking (Note 5)

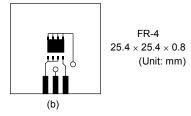


Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a)







Note 3:  $V_{DD} = 24 \text{ V}$ ,  $T_{ch} = 25^{\circ}C$  (initial),  $L = 100 \mu H$ ,  $R_G = 25 \Omega$ ,  $I_{AR} = -40 \text{ A}$ 

Note 4: Repetitive rating: pulse width limited by max channel temperature

Note 5: O on lower left of the marking indicates Pin 1.

※ Weekly code: (Three digits)



Week of manufacture \_(01 for first week of year, continues up to 52 or 53)

Year of manufacture
 (One low-order digits of calendar year)

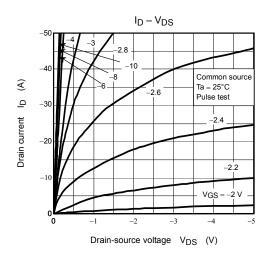
## Electrical Characteristics (Ta = 25°C)

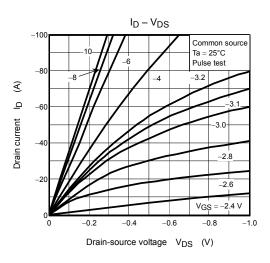
Cha	aracteristics	Symbol	Test Condition Min Typ. Max		Max	Unit	
Gate leakage cur	rrent	I <sub>GSS</sub>	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_	—	±10	μA
Drain cut-OFF cu	irrent	I <sub>DSS</sub>	$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	_	_	-10	μA
Gate threshold voltage Drain-source ON resistance Forward transfer admittance nput capacitance Reverse transfer capacitance		V (BR) DSS	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-30	_	_	V
Diam-source bre	akuown vollage	V (BR) DSX	$I_D = -10 \text{ mA}, V_{GS} = 20 \text{ V}$	-13	-     -     -10       -30     -     -       -13     -     -       -0.8     -     -2.0       -     5.2     6.8       -     3.1     4.2       22.5     45     -       -     7880     -       -     1340     -       -     15     -       -     125     -       -     596     -	v	
Gate threshold ve	oltage	V <sub>th</sub>	$V_{DS} = -10 \text{ V}, \text{ I}_{D} = -1 \text{ mA}$	-0.8	_	-2.0	V
	registeres	Decker	$V_{GS} = -4 V$ , $I_D = -20 A$	_	5.2	6.8	
Drain-source ON	rain-source ON resistance		$V_{GS} = -10 \text{ V}, \text{ I}_{D} = -20 \text{ A}$	_	3.1	4.2	mΩ
Forward transfer	admittance	Y <sub>fs</sub>	$V_{DS} = -10 \text{ V}, \text{ I}_{D} = -20 \text{ A}$			—	S
Input capacitance	out capacitance		$V_{DS} = -10 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$		7880		pF
Reverse transfer capacitance		C <sub>rss</sub>		_	1340		
Reverse transfer capacitance Output capacitance		C <sub>oss</sub>		_	1450	—	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Rise time	tr	$V_{CS} = 0 V_{T} I_{D} = -20A$	_	15	_	
	_	13	_				
	_	ns					
	Turn-OFF time	t <sub>off</sub>	55	_	596	_	
		Qg	55 00	_	184	_	nC
Gate-source charge 1		Q <sub>gs1</sub>			12		
		Q <sub>gd</sub>		_	58		

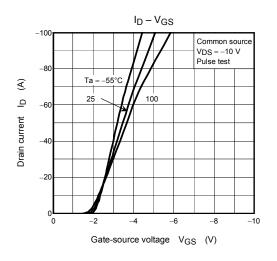
## Source-Drain Ratings and Characteristics (Ta = 25°C)

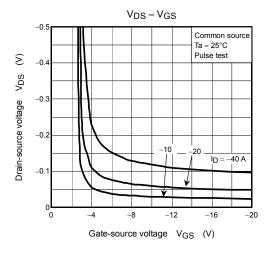
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit	
Drain reverse current	Pulse	(Note 1)	I <sub>DRP</sub>	—	_	_	-120	А
Forward voltage (diode)			V <sub>DSF</sub>	$I_{DR} = -40$ A, $V_{GS} = 0$ V		_	1.2	V

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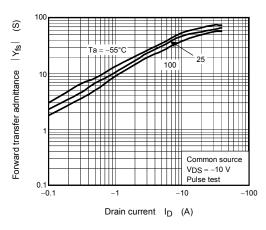




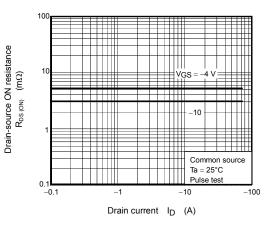




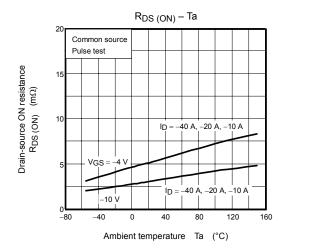


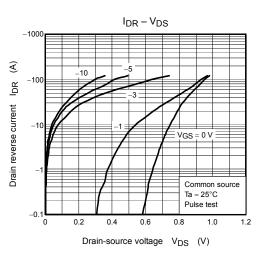


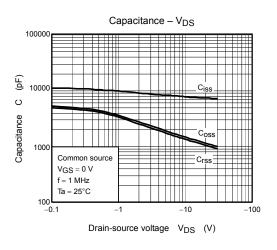
 $R_{DS(ON)} - I_D$ 

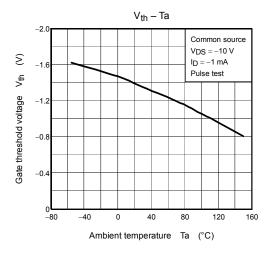


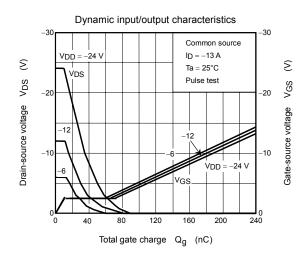
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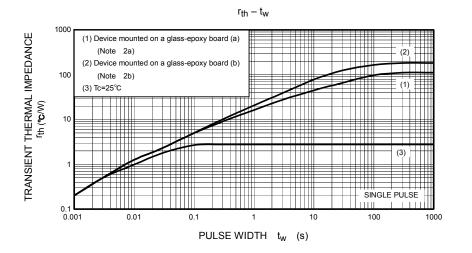


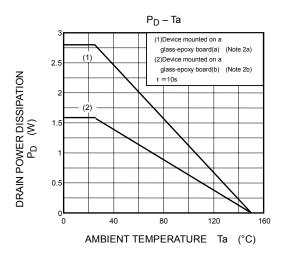


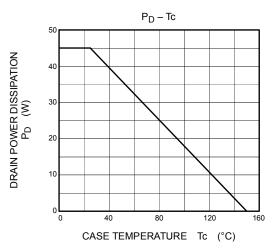


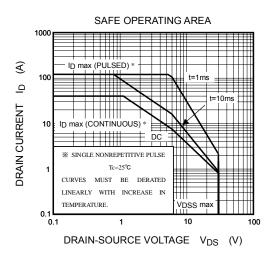












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